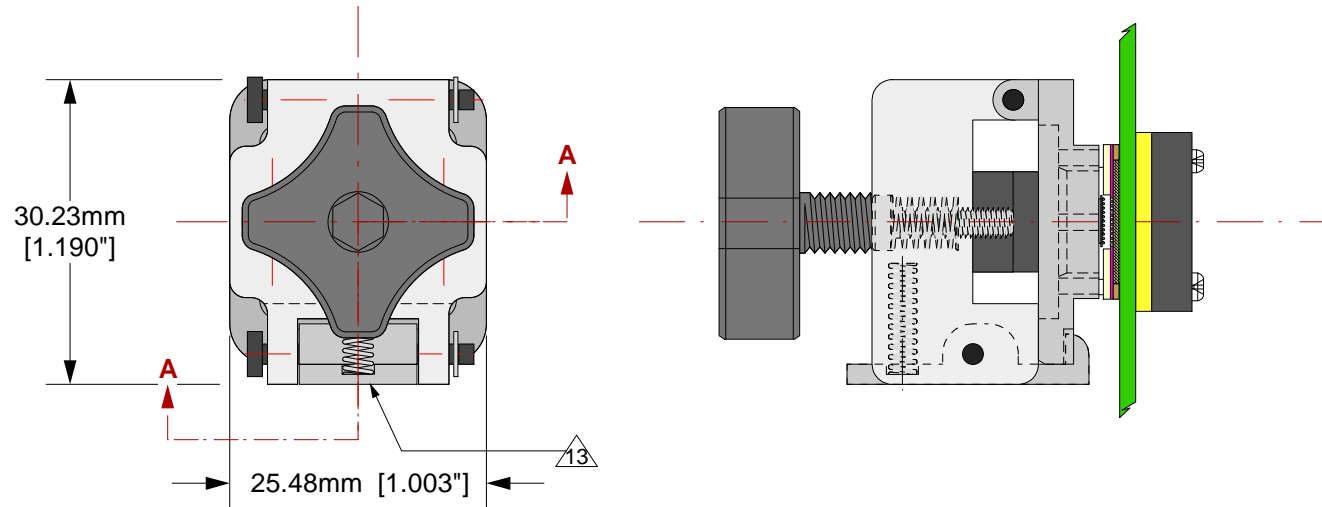
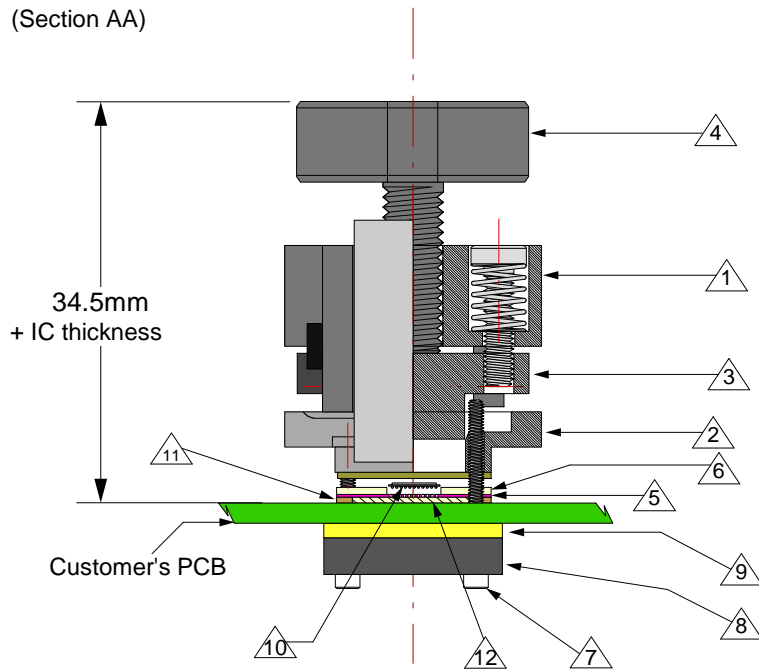


Top View



Side View
(Section AA)



Features

- Directly mounts to target PCB (needs tooling holes) with hardware
- Minimum real estate required
- Compression plate distributes forces evenly
- Clamshell lid

Materials:

- 1 Clam Shell Lid: Black anodized Aluminum. Height = 16.5 mm.
- 2 Socket Base: Black anodized Aluminum. Height = 6 mm.
- 3 Compression Plate: Black anodized Aluminum. Thickness = 8.5 mm.
- 4 Compression Screw: Clear anodized Aluminum. Height = 25 mm, Fluted Knob
- 5 Ball Guide: Kapton polyimide.
- 6 IC Guide: Ultem
- 7 Socket Base Screw: Socket Head Cap Screw, alloy steel with black oxide finish, 0-80 Thread, 5/8" long.
- 8 Backing Plate: Black anodized Aluminum. Thickness= 4mm
- 9 Insulation Plate: FR4/G10
- 10 Customer's BGA IC
- 11 Elastomer Guide: Non-clad FR4. Thickness = 0.475mm.
- 12 Elastomer: 20 micron dia gold plated brass filaments arranged symmetrically in a silicone rubber (63.5 degree angle). Thickness = 0.5mm.
- 13 Latch: Black anodised Aluminum.

CG-BGA-5003 Drawing

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Tele: (952) 229-8200
www.ironwoodelectronics.com

Status: Released

Scale: 1.33:1

Rev: A

Drawing: Vinayak R

Date: 2/16/10

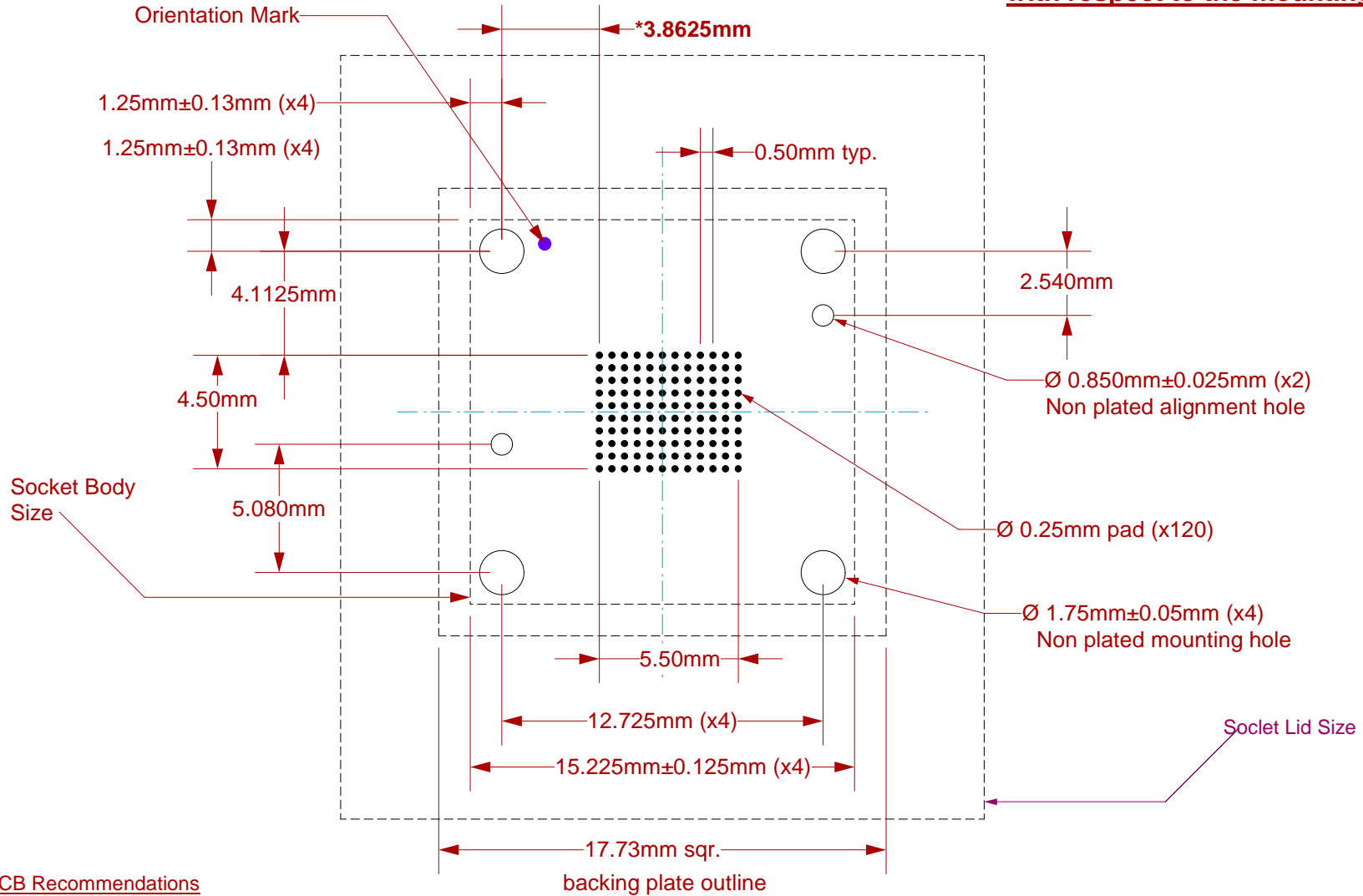
File: CG-BGA-5003 Dwg

Modified:

All Tolerances: ±0.125mm (unless stated otherwise). Materials and specifications are subject to change without notice.

Recommended PCB Layout
Top View

***Note: BGA pattern is not symmetrical with respect to the mounting holes.**




Target PCB Recommendations

Total thickness: 1.6mm min.
 Plating: Gold or Solder finish
 PCB Pad height: Same or higher than solder mask

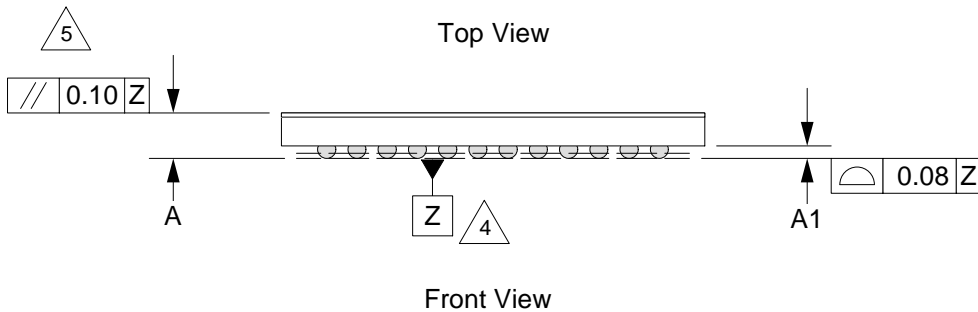
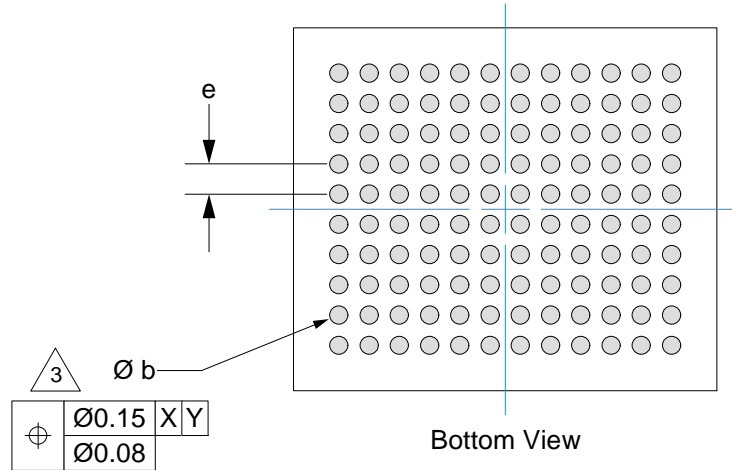
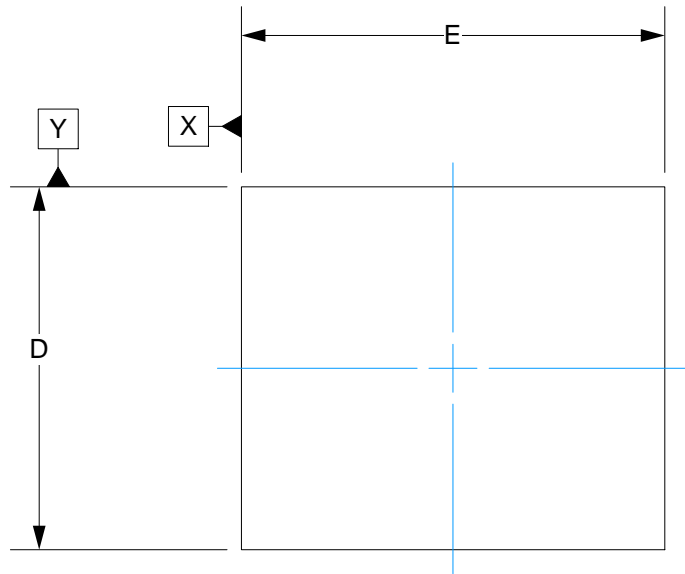
All dimensions are in mm unless stated otherwise

Recommended PCB Layout Tolerances: ±0.025mm [±0.001"] unless stated otherwise.

	CG-BGA-5003 Drawing	Status: Released	Scale: 4:1	Rev: A
	© 2010 IRONWOOD ELECTRONICS, INC. Tele: (952) 229-8200 www.ironwoodelectronics.com	Drawing: Vinayak R	Date: 2/16/10	
		File: CG-BGA-5003 Dwg	Modified:	

Recommended PCB Layout Tolerances: ±0.025mm [±0.001"] unless stated otherwise.


Compatible BGA Spec



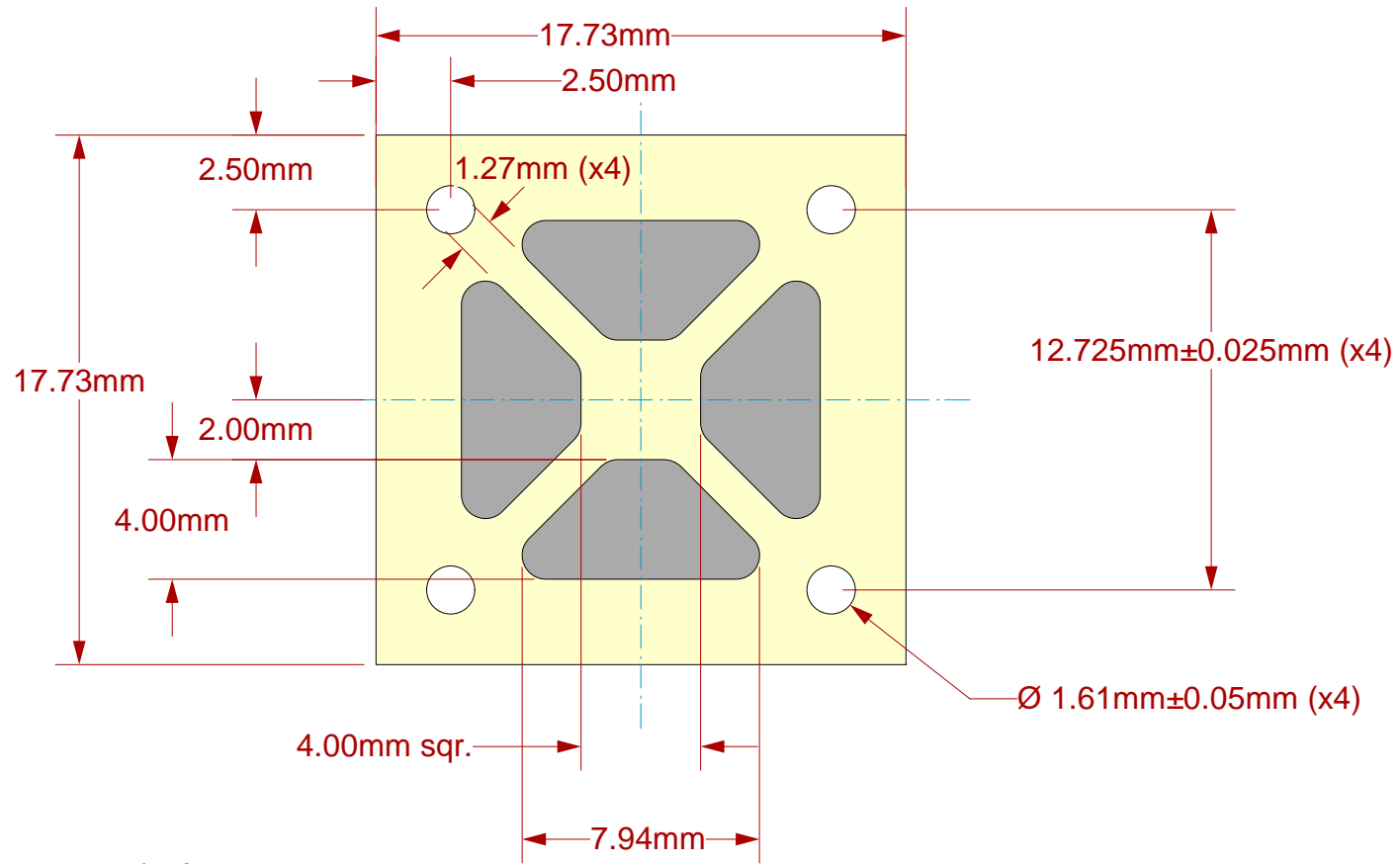
1. Dimensions are in millimeters.
 2. Interpret dimensions and tolerances per ASME Y14.5M-1994.
- 3. Dimension b is measured at the maximum solder ball diameter, parallel to datum plane Z.
 - 4. Datum Z (seating plane) is defined by the spherical crowns of the solder balls.
 - 5. Parallelism measurement shall exclude any effect of mark on top surface of package.

DIM	MIN	MAX
A		3.00
A1	0.225	0.25
b	0.30	
D	6.0 BSC	
E	7.0 BSC	
e	0.5 BSC	

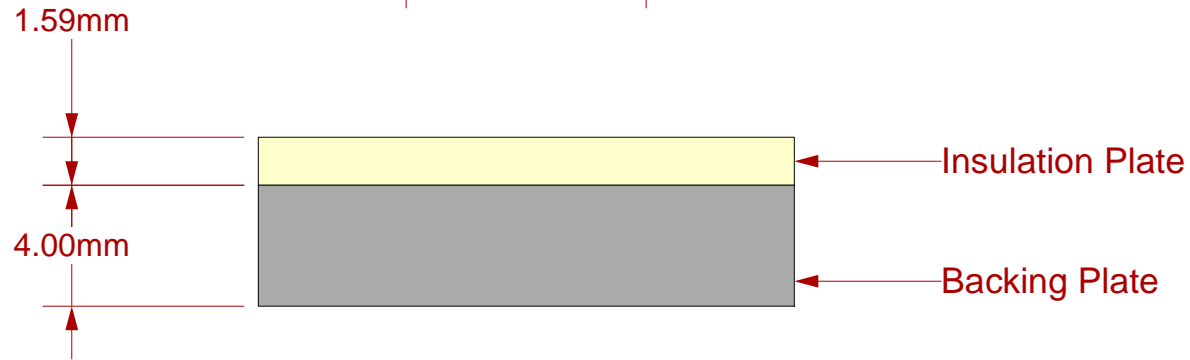
10 x 12 array

 <p>© 2010 IRONWOOD ELECTRONICS, INC. Tele: (952) 229-8200 www.ironwoodelectronics.com</p>	CG-BGA-5003 Drawing		Status: Released	Scale: 8:1	Rev: A	
	Drawing: Vinayak R			Date: 2/16/10		
	File: CG-BGA-5003 Dwg			Modified:		


Top View



Side View



Description: Backing Plate with Insulation Plate

	CG-BGA-5003 Drawing	Status: Released	Scale: 4:1	Rev: A
	© 2010 IRONWOOD ELECTRONICS, INC. Tele: (952) 229-8200 www.ironwoodelectronics.com	Drawing: Vinayak R		Date: 2/16/10
		File: CG-BGA-5003 Dwg	Modified:	

All dimensions are in mm.
All tolerances are +/- 0.125mm.
(Unless stated otherwise)